

S1 Passive Components Steering Committee Meeting Minutes  
 Sheraton Austin at the Capitol  
 Austin, Tx  
 Tuesday Sept. 28, 2010

**1.0 Call to Order - Circulate Membership Roster**

Meeting called to order at 8:05 am by Chairman Mike Lauri.

**2.0 Committee Organization and Procedures**

2.1 Membership Intros were conducted and Roster circulated.

The attendance was as follows:

<u>NAME</u>	<u>COMPANY</u>
Michael Lauri	IBM
Darin Glenn	Vishay
Bill Balliette	Faradox Energy Storage
Joe Biernacki	SEI Electronics
Laird Macomber	CDE
Brian Piscitelli (by phone)	KOA
William Gisseler	TDK
Ed Mikoski	ECA
McHargue	Murata
Mike Cannon (by phone)	TDK

A quorum was present. 7 of 8 member companies present at meeting.

<u>Member Organizations Present</u>	<u>Present at the Meeting (Fall 2010)</u>	<u>Present at the Meeting (Spring 2010)</u>	<u>Present at this Meeting (Fall 2009)</u>
Cornell Dubilier	Y	Y	Y
IBM	Y	Y	Y
Kemet	N	Y	Y
KOA Speer Electronics	Y	Y	Y
SEI Electronics	Y	Y	Y
TDK	Y	Y	N
Vishay	Y	Y	Y
Murata Electronics	Y	N	Y

<u>Other Organizations Present</u>
ECA
Faradox Energy Storage

## **2.1 and 2.2 Approval of Agenda and Previous Minutes – Approved Unanimously**

## **2.3 Correspondence – NONE**

**2.4 Review of Committees Scope-** To provide leadership and direction for passive component standards engineering working groups. The Committee will offer an opportunity for creating a unifying environment for interaction between all passive component users and producers. No changes required at this time.

## **3.0 ECA Environmental Update – ECA**

Ed Mikoski gave a report. JIG (Joint Industry Guide) 101 edition 3.1 is now final and was published in Sept 13,2010. This document lists a compilation of banned material requirements for the electronics industry sector. It now has the 38 new REACH items in the tables. Ed asked if you had any inputs to this document, to bring them to his attention and he will get it to the correct folks for review. Laird brought to Ed's attention about the banned materials coming from the Congo and if this was being considered to be added into this document. Ed will bring this up for possible inclusion into this document. Ed also talked about the QC080K which is an ISO type for management system compliance and companies are being certified to it now.

## **4.0 Old Business**

**4.1** Mike Lauri of IBM updated the group on the revision of J-STD-075 Classification of Non-IC Electronic Components for Assembly processing. This document is controlled by the ECA and the committee chairs are Paul Krystek/Mike Lauri. The spec is not going to be revised now. There was discussion about revising J-STD-075 for connectors, but the connector committee has confirmed that their PTH parts are not PSL sensitive. They are discussing SMT connectors and any studies needed to help revise this document as needed. At this point in time, the committee will probably revise this document in the 5 year review and at that time update any sections needing updates, along with adding a section on component rework. The plan is to eventually have the marking requirements moved from the J-STD-075 to J-STD-033 for clarity.

ECA Ed Mikoski brought up that on IHS the IPC copy of J-STD075 does not include the ECA logo and it should be there. ECA will take action item to follow up with IHS and IPC to get it added since it is losing revenue due to this oversight.

**4.2** JEP709, 'A Guideline for Defining 'Low-Halogen' Solid State Devices (Removal of BFR/CFR/PVC)', updated the status of the BoD ballot and the appeal by Apple to the release of this document. The document was submitted to the JEDEC Board of Directors (BoD) for their vote on whether proper procedures were followed in the generation of this publication. While the ballot was out, Apple submitted an appeal to BoD stating 3 specific items. Note, this is the first ever appeal of a JEDEC document, published or proposed. During the BoD ballot, the representative of JC-10 reversed their comments from the committee ballot, which in turn eliminated 2 of Apple's objections. The BoD ballot then closed with no other comments, and thus now stands with all 'Yes' votes. During the BoD meeting, the BoD decided to hold their ruling on the document until the

appeal by Apple is resolved. A hearing in front of 3 (impartial) BoD members will be held September 27th. At this time Apple will present their position, and the committee will present the position of the 14.4 committee. Depending on the finding of the panel, which should be released a few weeks after the hearing, the document could go back to committee to make changes per the panels suggestions, or could be published soon after, if the panel finds against Apple.

It was mentioned during the meeting that ECA (the US standards body for passives, connectors, et al) may be interested in working with JEDEC to make JEP709 a joint document to cover the commodities represented by ECA membership. Also discussed was the fact that IPC has reinstated an effort for a low halogen document that again covers all commodities, and included would be a tier approach, one similar to JEP-709 (covering just BFRs, CFRs, and PVC) and a second that covers elemental Cl and Br

4.3 Joint meetings - Did not discuss the possible joint meeting location for ECA, JEDEC and IPC in the 2010 timeframe to work on more joint standards

4.4 Ed Mikoski of ECA gave a report on the activities of INEMI and agreed to help wherever possible to in drafting a roadmap for passive components. The individual chapters in this roadmap have been turned over to the coordinators for finalization now. Since there was not much runway in 2010, ECA will participate within each P panel group committee in the next 2 year cycle of the INEMI roadmap. ECA is in the process now of the rewrite for the passive section.

## **5.0 New Business**

5.1 ECA merger activity. Ed reported that ECA is trying to merge with NEDA the national electronic distributor association. The target for this merger is Jan 1, 2011 with the new title of this group being EICA= Electronics Industry Components Association We found out that NEDA does not publish specifications, but rather only guidelines so this will be a change for them. They are heavily focused on the electronic side, bookings, billings, and reporting of purchased electronics and forms, where as ECA is focused on passive component specifications.

5.2 Lanney from Murata brought up a concern about the newly revised AEC Q200 automotive qualification document. It appears that with all the layoffs and lost key personal in that industry this document was rushed to be revised and has errors in it. Specifically the passives cannot meet the terminal strength requirements on ultra small size ( 0402, 0201, 01005) size components. He recommended we send correspondence to the AEC committee to get this fixed. S1 Chairmen deferred this issue to the ceramic capacitor committee chairmen since it affects ceramic capacitor manufactures the most.

**6.0 Future Meetings** – The next meeting, Spring 2010, will probably be in Orlando, FL again, with hotel to TBD.

The committee opted to let ECA pick the next Fall 2011 meeting location. With the rotation, this meeting should be held on the west coast but most companies that attend are east coast stationed.

**8.0 Action Items –**

ECA to present the passives portion of INEMI roadmap at the next S1 meeting.

**9.0 Adjournment –** Meeting was adjourned at 10:00 AM.